Power Transistors

Panasonic

10.0±0

5.5±0

6.7±0.3

ä

Unit: mm

4.2±0.

1.3±0.2

0.5+0.2

Collector 3: Emitter EIAJ: SC-67 OTO-220F-A1 Package

2.7±0

4

φ 3.1±0.1

1.4±0.

5.08+0.5

2SD1445A

Silicon NPN epitaxial planar type

For power amplification, power switching and low-voltage switching Complementary to 2SB0948A

Features

4

- Low collector-emitter saturation voltage V_{CE(sat)}
- High-speed switching
- Satisfactory linearity of forward current transfer ratio h_{FE}
- Large collector current I_C
- Full-pack package which can be installed to the heat sink with one screw.

| Absolute Maximum Ratings $T_C = 25^{\circ}C$ | | | | | | | | |
|--|------------------|-------------|------|---|---|--|--|--|
| Parameter | Symbol | Rating | Unit | | | | | |
| Collector-base voltage (Emitter open) | V _{CBO} | 50 | V | | | | | |
| Collector-emitter voltage (Base open) | V _{CEO} | 40 | V | | | | | |
| Emitter-base voltage (Collector open) | V _{EBO} | 5 | V | | | | | |
| Collector current | I _C | 10 | A | | | | | |
| Peak collector current | I _{CP} | 20 | A | | | | | |
| Collector power | Pc | 40 | W | | | | | |
| dissipation $T_a = 25^{\circ}C$ | | 2.0 | | | | | | |
| Junction temperature | Tj | 150 | °C | | | | | |
| Storage temperature | T _{stg} | -55 to +150 | °C | × | ~ | | | |

Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

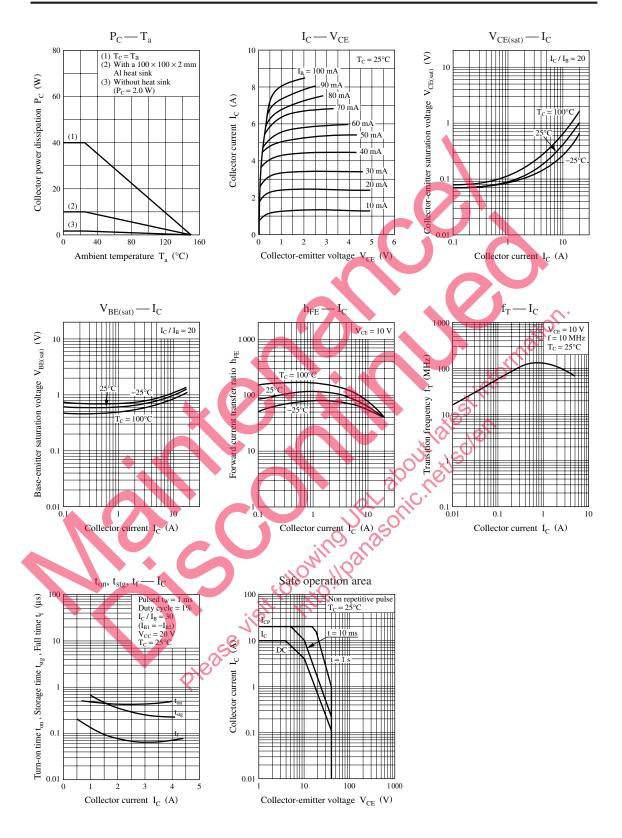
| Collector current | I _C | 10 A & | | KO Ì | TO-220F-A1 Package | |
|---|--|---|-----|-------------|--------------------|------|
| Peak collector current | I _{CP} | 20 A | | 10. | | |
| Collector power | Pc | 40 W | S | • | | |
| dissipation $T_a = 25^{\circ}C$ | | 2.0 | | 2 | | |
| Junction temperature | Tj | 150 °C | | | | |
| Storage temperature | $\begin{array}{c c c c c c c c c c c c c c c c c c c $ | | | | | |
| Electrical Characteristics T | $c = 25^{\circ}C$ | ±3°C PL nic | ίι. | [| | |
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
| Collector-emitter voltage (Base open) | V _{CEO} | V_{CEO} $I_{C} = 10 \text{ mA}, J_{B} = 0$ | | | | V |
| Collector-base cutoff current (Emitter open) | I_{CBO} $V_{CB} = 50$ V, $I_E = 0$ | | | | 50 | μΑ |
| Emitter-base cutoff current (Collector open) | I _{EBO} | | | | 50 | μΑ |
| Forward current transfer ratio | h _{FE1} | h_{FE1} $V_{CE} = 2$ $V_{CE} = 0.1$ A | | | | — |
| | h _{FE2} * | $h_{FE2} = 2 V, I_C = 3 A$ | | | 260 | |
| Collector-emitter saturation voltage | VeE(sat) | $I_{\rm C} = 10 \text{ A}, I_{\rm B} = 0.33 \text{ A}$ | | | 0.6 | V |
| Base-emitter saturation voltage | V _{BE(sat)} | $I_{C(sat)}$ I _C = 10 A, I _B = 0.33 A | | | 1.5 | V |
| Transition frequency | f _T | Γ V _{CE} = 10 V, I _C = 0.5 A, f = 10 MHz | | 120 | | MH |
| Collector output capacitance (Common base, input open circuited) | C _{ob} | $V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$ | | 200 | | pF |
| Turn-on time | t _{on} | $I_C = 3 A, I_{B1} = 0.1 A, I_{B2} = -0.1 A,$ | | 0.3 | | μs |
| Storage time | t _{stg} | $V_{CC} = 20 V$ | | 0.4 | | μs |
| Fall time | t _f | 1 | | 0.1 | | μs |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

| Rank | R | Q | Р |
|------------------|-----------|-----------|------------|
| h _{FE2} | 60 to 120 | 90 to 180 | 130 to 260 |

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